

# MB2301\_RF\_Miniboard\_STM32WBA25\_QFN48\_SMPS

MB2301

## Table of contents

Sheet 1: Project overview (this page)

Sheet 2: Top

Sheet 3: STM32 microcontroller I/Os & Clock

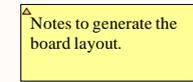
Sheet 4: RF & Power Management

## Legend

General comment such as function title, configuration, ...

Text to be added to silkscreen.

Warning text.



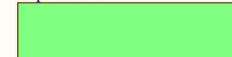
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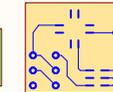
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Top.SchDoc



HW1



MB2301

HW3



N/A

HW4

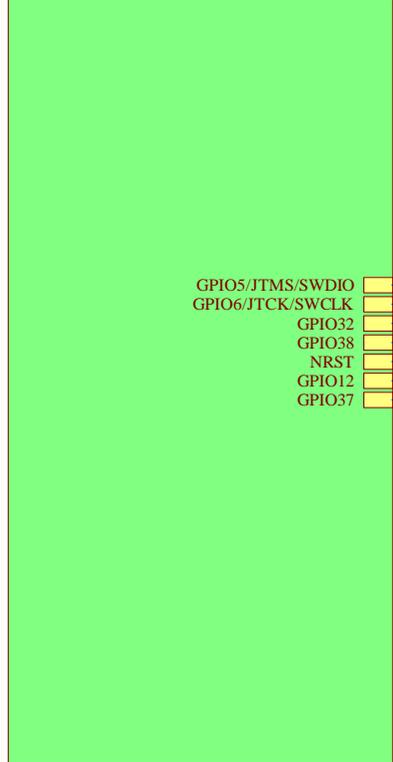


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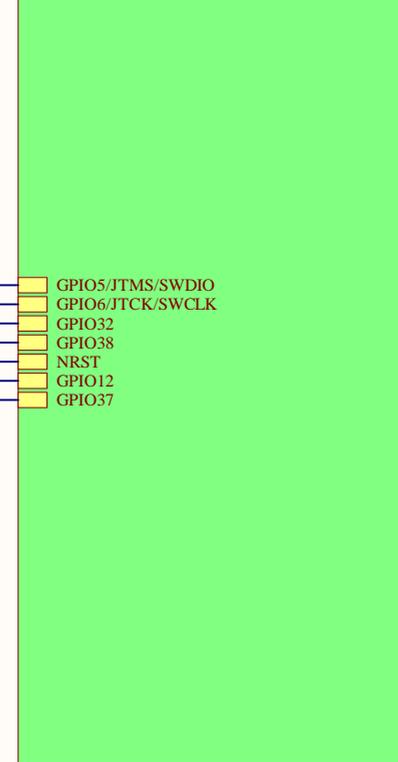
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Project: <b>MB2301_RF_Miniboard_STM32WBA25_QFN48_SMPS</b>		
Variant: <b>WBA23CE</b>		
Revision: <b>A-01</b>		Reference: <b>MB2301</b>
Size: <b>A4</b>	Date: <b>30-09-2025</b>	Sheet: <b>1</b> of <b>4</b>

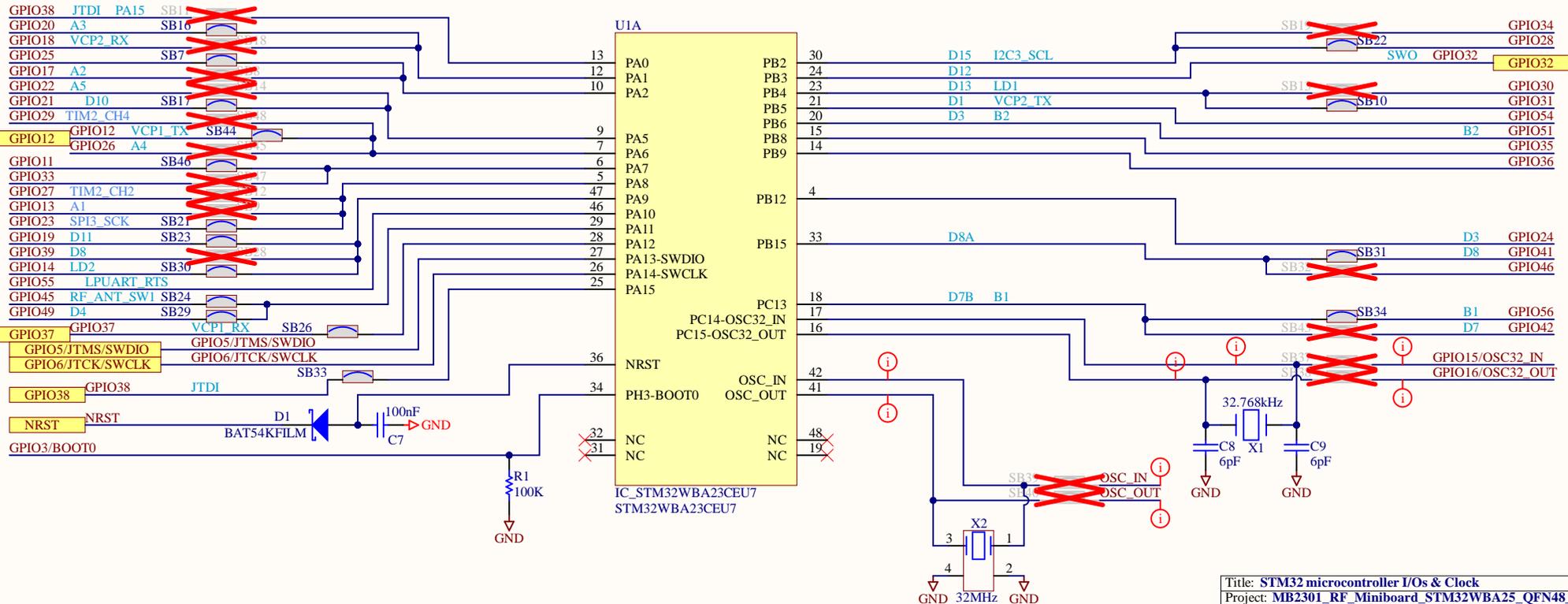
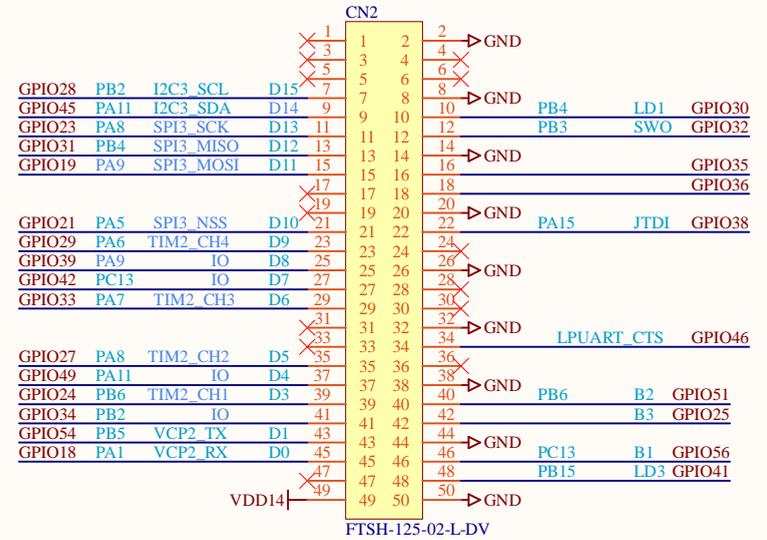
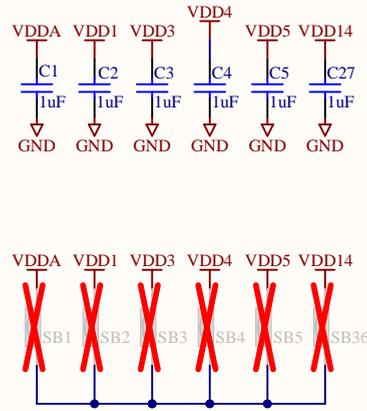
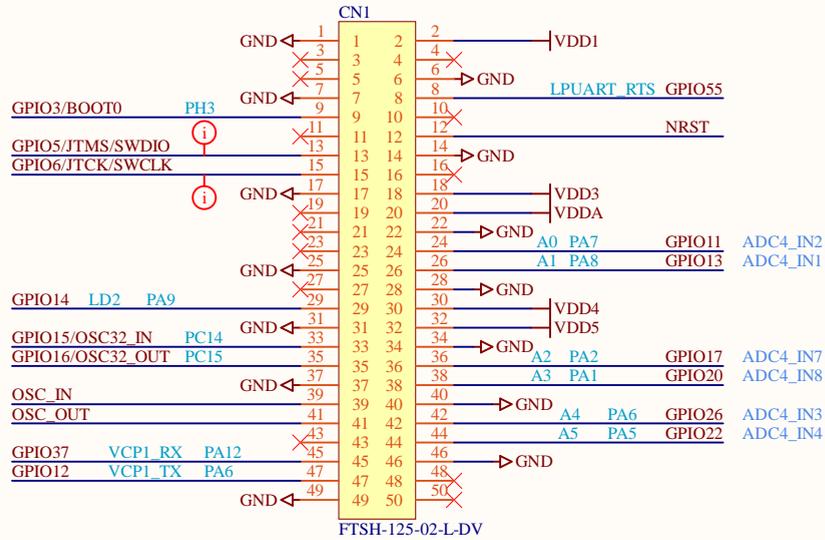


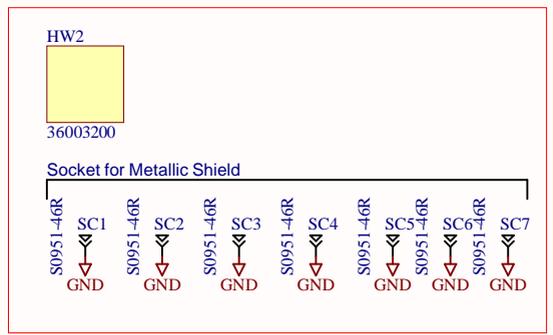
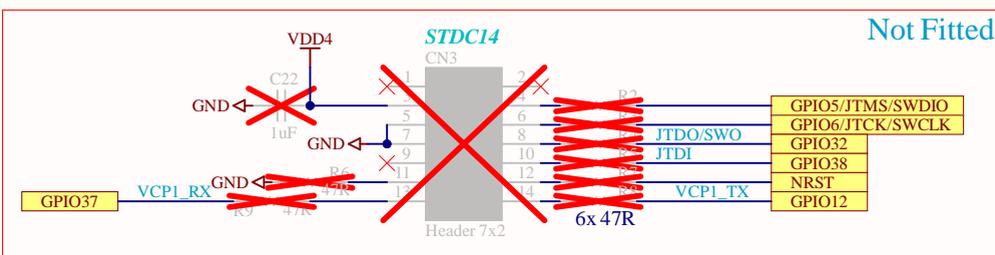
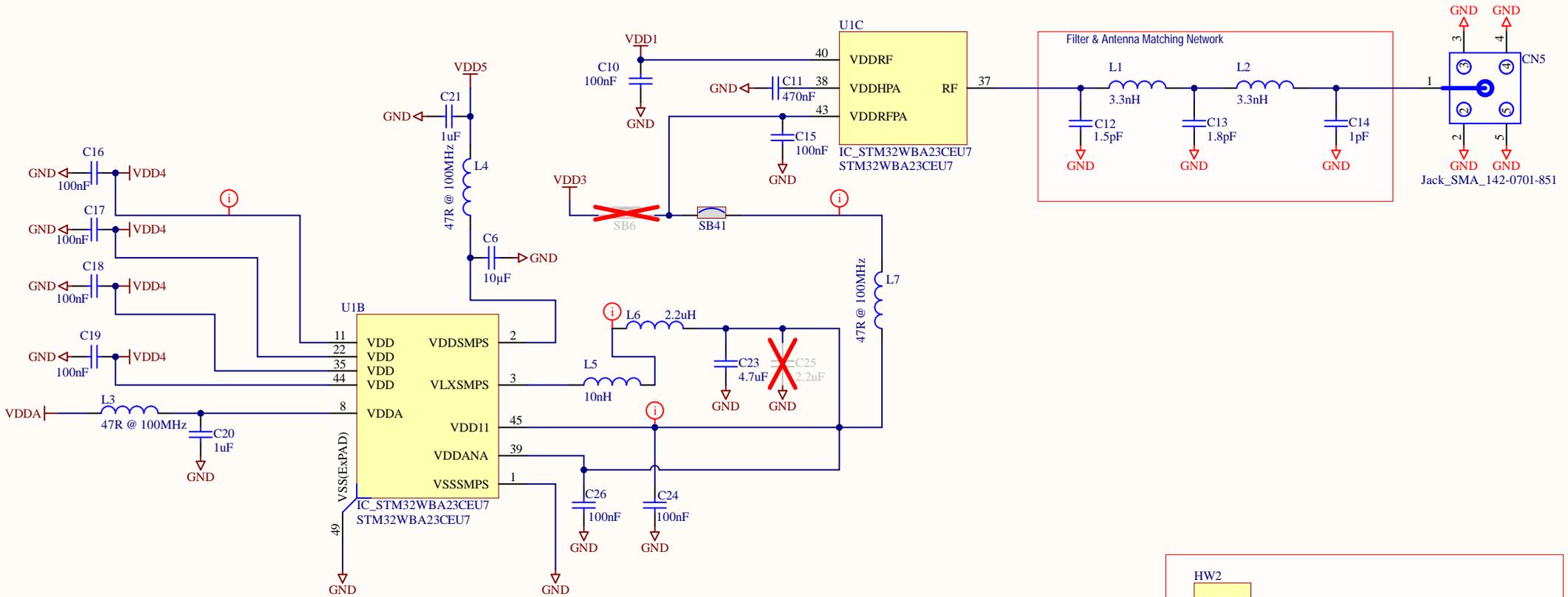
STM32 microcontroller I/Os & Clock

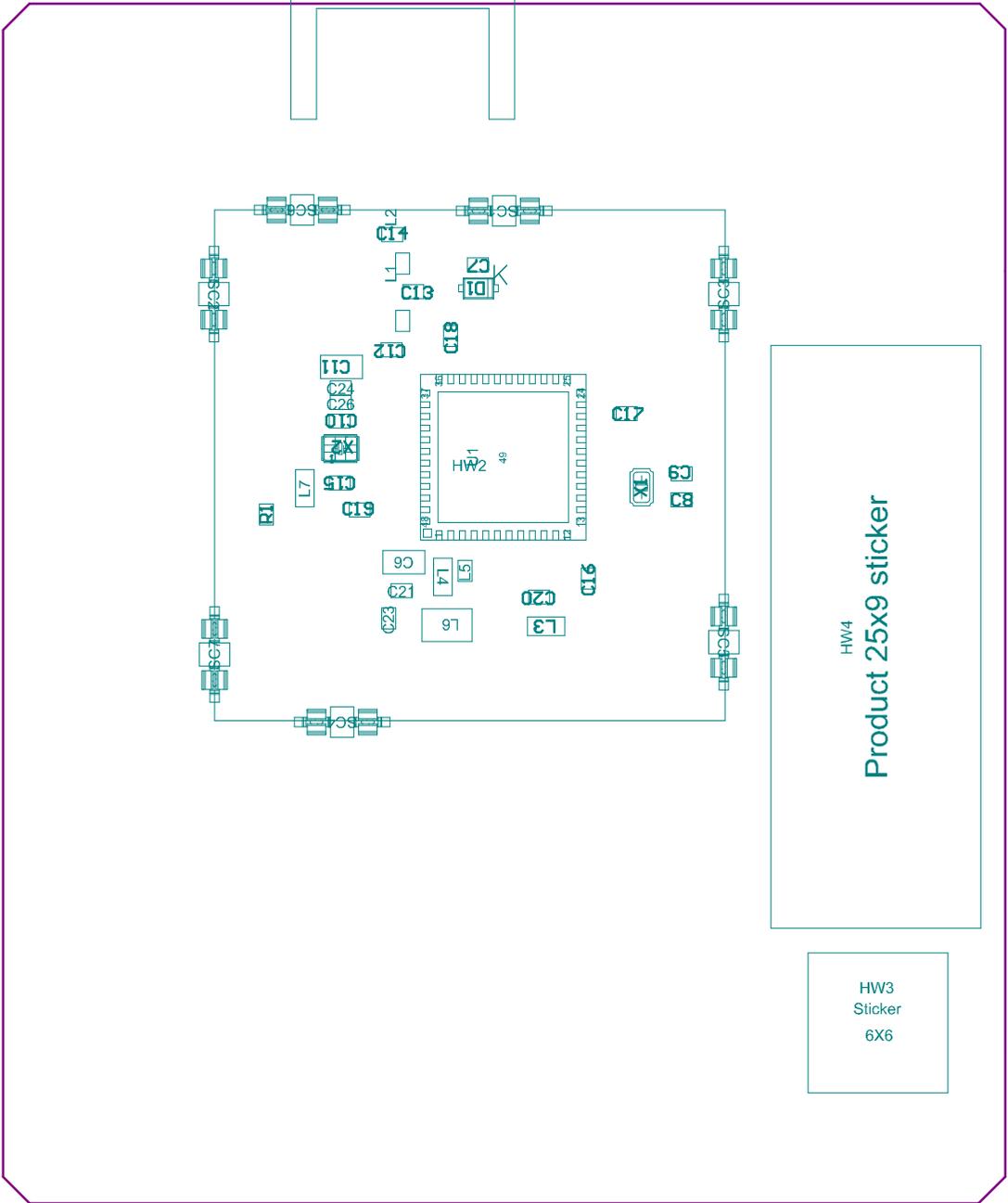
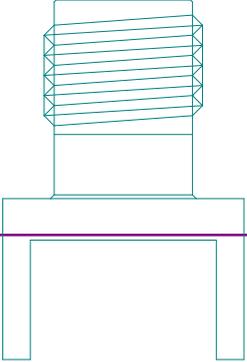


RF & Power Management Schematic



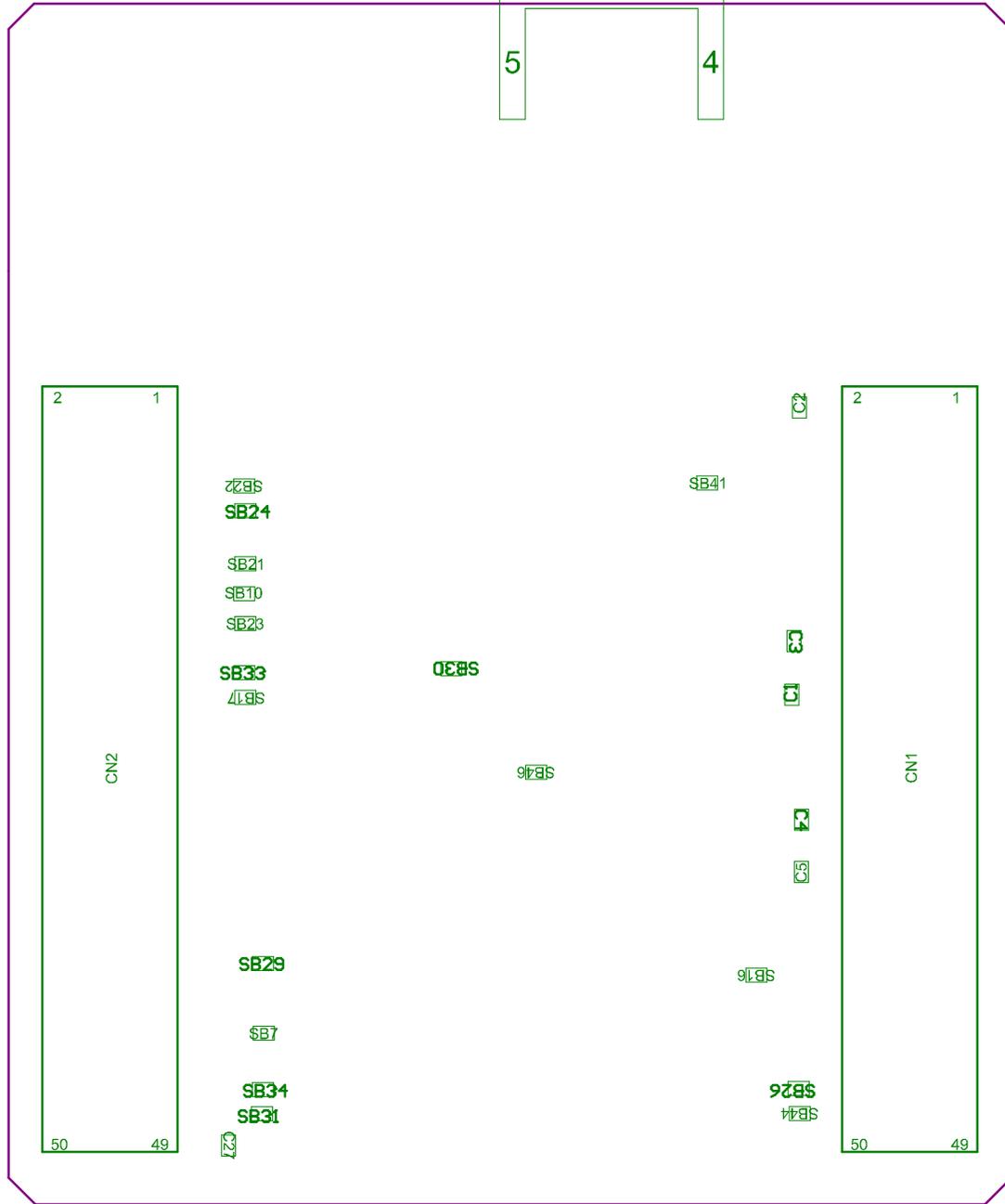
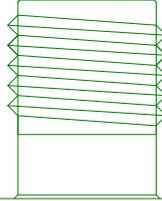




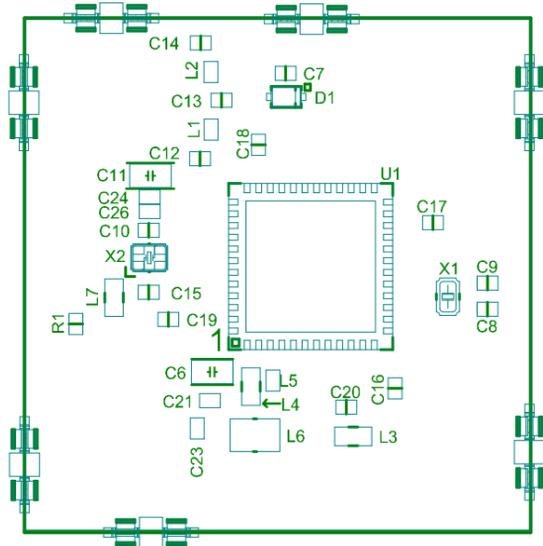
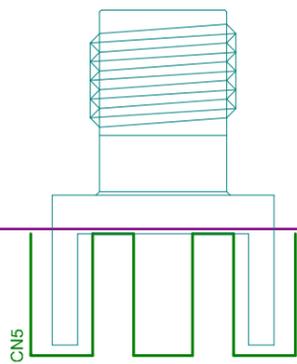


HW4  
Product 25x9 sticker

HW3  
Sticker  
6X6







Product 25x9 sticker

Sticker  
6X6

**MB2301A**

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0,018mm	4.2	
1	Top Layer		0,041mm		
	Dielectric 1	FR-4	0,076mm	3.7	
2	Internal 1		0,030mm		
	Dielectric 3	FR-4	1,270mm	4.5	
3	Internal 2		0,030mm		
	Dielectric 2	FR-4	0,076mm	3.7	
4	Bottom Layer		0,041mm		
	Bottom Solder	Solder Resist	0,018mm	4.2	
	Bottom Overlay				

mm006,1

Total board thickness:

